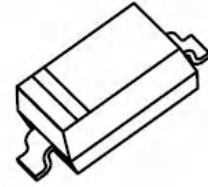




### Discription

The PESD5V0S1BB protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD. It gives designer the flexibility to protect one bi-directional line in applications where arrays are not practical.



SOD-523

### Features

- ★ Reverse stand-off voltage: 5V Max
- ★ Low leakage current: nA Level
- ★ Low Clamping Voltage
- ★ Response time is typically
- ★ IEC61000-4-2 Level 4 ESD Protection



Circuit Diagram

### Ordering information

Product ID	Pack	Qty(PCS)
PESD5V0S1BB	SOD-523	3000

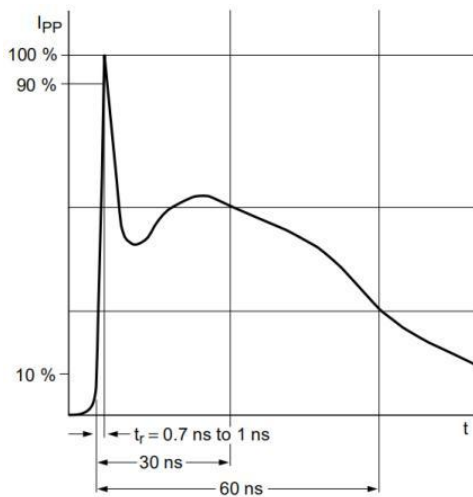
### Absolute Ratings (T<sub>amb</sub>=25°C )

Symbol	Parameter	Value	Units
P <sub>PP</sub>	Peak Pulse Power (t <sub>p</sub> = 8/20 μ s)	100	W
T <sub>L</sub>	Maximum lead temperature for soldering during 10s	260	°C
T <sub>stg</sub>	Storage Temperature Range	-55 to +155	°C
T <sub>op</sub>	Operating Temperature Range	-40 to +125	°C
T <sub>j</sub>	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD)	air discharge ± 30 contact discharge ± 30	KV
	IEC61000-4-4 (EFT)	11	A

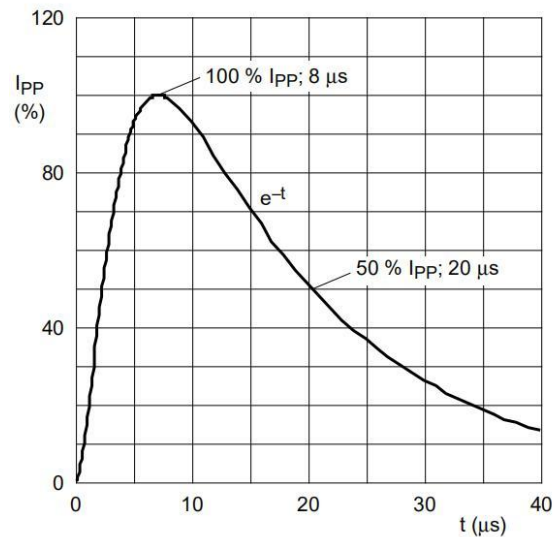


**Electrical Characteristics** Ratings at 25°C ambient temperature unless otherwise specified. VF = 0.9V at IF = 10mA

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Reverse Working Voltage	$V_{RWM}$	--	--	5.0	V	
Breakdown Voltage	$V_{BR}$	5.6	--	--	V	$I_T=1mA$
Leakage Current ILeak	$I_R$	--	--	100	nA	$V_{RWM}=5V$
Clamping Voltage	$V_C$	--	--	9.0	V	$I_{PP}=11A, T_p=8/20\mu s$
Junction Capacitance	$C_J$	--	20	25	pF	$V_R=0V, f=1MHz$



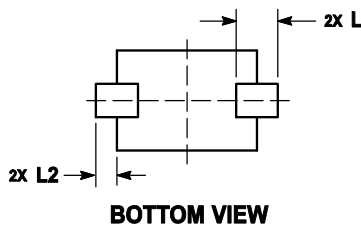
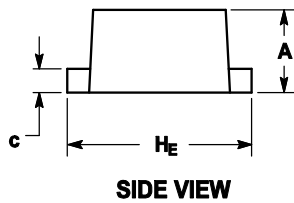
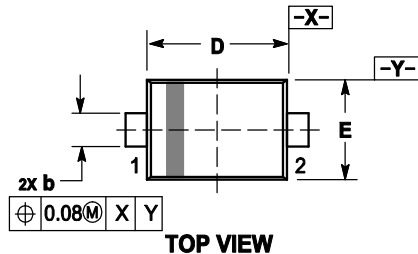
**IEC61000-4-2 Waveform**



**IEC 61000-4-5 Waveform( 8/20μs pulse)**



## OUTLINE AND DIMENSIONS

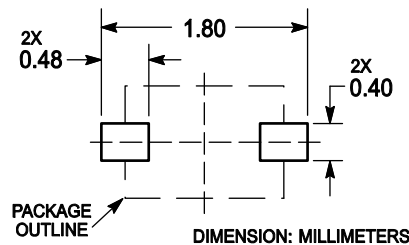


### Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.50	0.60	0.70	0.020	0.024	0.028
b	0.25	0.30	0.35	0.010	0.012	0.014
c	0.07	0.14	0.20	0.003	0.006	0.008
D	1.10	1.20	1.30	0.043	0.047	0.051
E	0.70	0.80	0.90	0.028	0.031	0.035
H <sub>E</sub>	1.50	1.60	1.70	0.059	0.063	0.067
L	0.30 REF			0.012 REF		
L <sub>2</sub>	0.15	0.20	0.25	0.006	0.008	0.010

## SOLDERING FOOTPRINT





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